



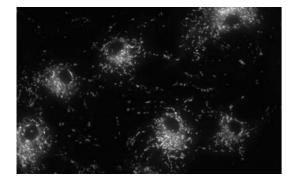
## **APPLICATION**

We have a diverse lineup of cameras that support a wide range of wavelengths from X-rays to the near-infrared and support a variety of applications.

### Life science

### Time-lapse imaging of live cells

Mitochondria in living cells are observed by long-time time-lapse imaging.



#### Micron-sized mouse kidney cells are observed by high-resolution imaging under an electron microscope.

Observation of mouse kidney cells



### Medical

### Medical diagnosis

The condition of the affected area is observed for diagnosis by infrared imaging.

The cross-sectional structure of the toothpick is clearly shown by



Synchrotron imaging

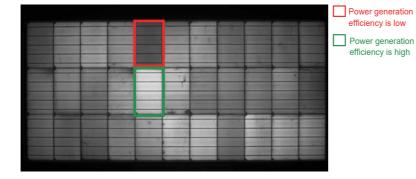
high-resolution X-ray imaging.

X-ray CT

### Semiconductor inspection

### Inspection of power generation efficiency of solar panel

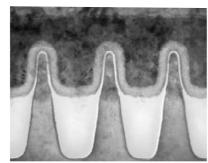
The power generation efficiency of a solar cell panel (1 m × 0.5 m) is observed by wide-field infrared imaging with an EL image.



### Electronic microscope

### Structure observation of semiconductor devices

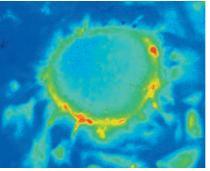
The interior structure of a semiconductor device is analyzed at the nano-level by high-resolution imaging using an electron microscope.



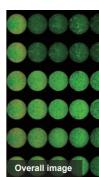
### — 20 nm

### Cardiomyocyte pulsation observation

The pulsation of cardiomyocytes associated with changes in calcium ion concentration is observed by high-speed imaging using fluorescence images.



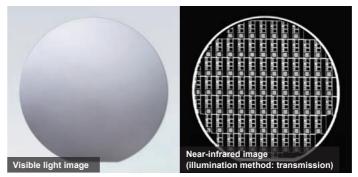
fluorescent images.



\* Displayed with pseudo color by image processing.

### Transmission observation of Si wafer

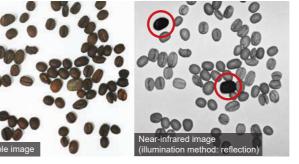
The pattern formed on the backside of the Si wafer is observed transmittedly through the front side by infrared imaging.

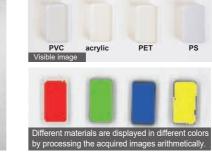


### Food inspection

### Foreign object detection

Small stones mixed in coffee beans that are difficult to see with visible light are detected by the infrared imaging.

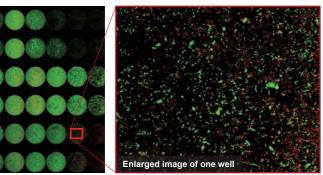






### Observation of cultured cells

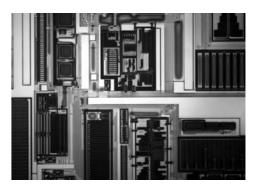
Cells cultured in one well of a microplate are observed by high-resolution imaging with



\* Displayed with pseudo color by image processing.

### Semiconductor device observation

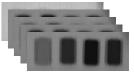
The pattern under the Si layer is observed by infrared imaging.



### Analysis/spectroscopy

### Material identification

Infrared imaging identifies materials that are difficult to distinguish in visible light, such as PVC, acrylic, PET, and PS.



Imaged at multiple wavelengths



\* Displayed with pseudo color by image processing.

### **CAMERA LINE UP**

Wavelength range	UV to near-infrared			v	/isible to near-infrared				Visible to near-infra	ared (for weak light)		Near-i	infrared	
Name	ORCA <sup>⊚</sup> II Digital CCD camera	ORCA-Fusion BT Digital CMOS camera	ORCA-Fusion Digital CMOS camera	ORCA-Flash4.0 V3 Digital CMOS camera	ORCA-Lightning Digital CMOS camera	ORCA-Flash4.0 LT+ Digital CMOS camera	ORCA-spark Digital CMOS camera	TDI camera	ImagEM <sup>®</sup> X2 EM-CCD camera	ImagEM X2-1k EM-CCD camera		InGaAs camera		InGaAs line scan Camera
Туре	C11090-22B	C15440-20UP	C14440-20UP	C13440-20CU	C14120-20P	C11440-42U30	C11440-36U	C10000-801	C9100-23B	C9100-24B	C14041-10U	C12741-03	C12741-11	C15333-10E
Appearance		Ĩ			0		Innum	<b>O</b>		00				O
Image sensor type	Area sensor		Area sensor				TDI sensor	Area	sensor		Area sensor		Line sensor	
Sensitivity wavelength range (nm)	200 to 1000	0 350 to 1000				200 to 1000	300 to	0 1100	950 to	o 1700	900 to 1550	950 to 1700		
(Spectral response: See P5)	0		0		6	<u>6</u>	<b>—0</b> —			<b>)</b>	—(	0		
Effective number of pixels (H × V)	1024 × 1024	2304 × 2304	2304 × 2304	2048 × 2048	4608 × 2592	2048 × 2048	1920 × 1200	2048 × 128	512 × 512	1024 × 1024	320 × 256	640 × 512	640 × 512	1024 × 1
Pixel size ((H) µm × (V) µm)	13 × 13	6.5 × 6.5	6.5 × 6.5	6.5 × 6.5	5.5 × 5.5	6.5 × 6.5	5.86 × 5.86	12 × 12	16 × 16	13 × 13		20 × 20		12.5 × 12.5
Effective area ((H) mm × (V) mm)	13.3 × 13.3	14.976 × 14.976	14.976 × 14.976	13.312 × 13.312	25.344 × 14.256	13.312 × 13.312	11.25 × 7.03	24.58 × 1.536	8.19 × 8.19	13.3 × 13.3	6.4 × 5.12	12.8 × 10.24	12.8 × 10.24	12.8 × 0.0125
Full well capacity (electrons) typ.*	80 000	15 000	15 000	30 000	38 000	30 000	33 000	80 000	370 000	400 000	-	-	300 000	-
Dynamic range typ.*	13 333:1	21 400:1	21 400:1	37 000:1	17 000:1	33 000:1	5000:1	1600:1	-	-	-	-	-	-
Cooling method	Forced-air cooled/ Water cooled	Forced-air cooled/ Water cooled	Forced-air cooled/ Water cooled	Forced-air cooled/ Water cooled	Forced-air cooled/ Water cooled	Forces-air cooled	-	-	Forced-air cooled/ Water cooled	Forced-air cooled/ Water cooled	Forced-air cooled	Forced-air cooled	Forced-air cooled/ Water cooled	-
Cooling temperature (°C)*	-75 (Water cooled)	-15 (Water cooled)	-15 (Water cooled)	-30 (Water cooled)	+20	+10	-	-	-100 (Water cooled)	-80 (Water cooled)	+10	+10	-70 (Water cooled)	-
Readout speed (frame/s) (Full resolution)*	3.15	89.1	89.1	100	121	30	64.9	50 kHz (Line rate)	70.4	18.5	216.6	59.774	7.2	40 kHz (Line rate)
Readout noise (electrons) rms typ.*	6	0.7	0.7	1.4	2	1.5	6.6	50	1 max.	1 max.	-	-	-	-
Dark current (electrons/pixel/s) typ.*	0.0012 (Water cooled)	0.7 (Water cooled)	0.2 (Water cooled)	0.006 (Water cooled)	15	0.6	-	-	0.0005 (Water cooled)	0.001 (Water cooled)	-	-	130 (Water cooled)	-
Interface	IEEE 1394b	CoaXPress (Dual CXP-6)/ USB 3.0	CoaXPress (Dual CXP-6)/ USB 3.0	Camera Link/USB 3.0	CoaXPress (Quad CXP-6)	USB 3.0	USB 3.0	Camera Link	IEEE 1394b	IEEE 1394b	USB 3.0	USB 3.0/EIA	Camera Link	Gigabit Ethernet
Applications	Analysis/spectroscopy Synchrotron imaging	Life science imaging Synchrotron imaging Electronic microscope	Life science imaging Semiconductor inspection Synchrotron imaging Electronic microscope	Life science imaging Semiconductor inspection Synchrotron imaging Electronic microscope	Life science imaging Synchrotron imaging	Life science imaging Semiconductor inspection	Life science imaging Synchrotron imaging	Life science imaging Semiconductor inspection	Life science imaging Synchrotron imaging	Life science imaging Synchrotron imaging	Semiconductor inspection Food inspection	Semiconductor inspection Analysis/spectroscopy	Life science imaging	Semiconductor inspection Food inspection

\* Depends on the mode and conditions. For details, refer to each product catalog.

Camera type	Board type camera for OEM								
Name	Scientific CMOS	board level camera	Digi	TDI board level camera					
Туре	C11440-62U	C11440-52U30	C13949-50U	C13770-50U	C13752-50U	C10000-A01			
Appearance	Ø	2	0	0	0	9			
Image sensor type	Area	sensor		TDI sensor					
Sensitivity wavelength range (nm)	350 t	o 1000		200 to 1000					
(Spectral response: See P5)		<b>3</b> ——							
Effective number of pixels (H × V)	2048 × 2048		4096 × 3008	2464 × 2056	2048 × 1544	2048 × 128			
Pixel size ((H) µm × (V) µm)	6.5	× 6.5		12 × 12					
Effective area ((H) mm × (V) mm)	13.312 × 13.312		14.13 × 10.37	8.50 × 7.09	7.06 × 5.32	24.53 × 1.536			
Full well capacity (electrons) typ.*	30 000			80 000					
Dynamic range typ.*	20 000:1	18 000:1		4565:1		1600:1			
Readout speed (frame/s) (Full resolution)*	30		15	40	65	50 kHz (Line rate)			
Readout noise (electrons) rms typ.*	2.1 2.3			50					
Interface	US	B 3.0		Camera Link					
Applications	plications Contact us Contact us		Contact us Contact us Contact us		Life science imaging Semiconductor inspection				

### For X-ray





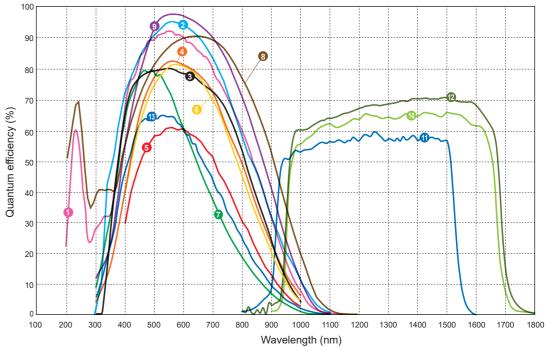




USB 3.0

Synchrotron imaging

### Spectral response



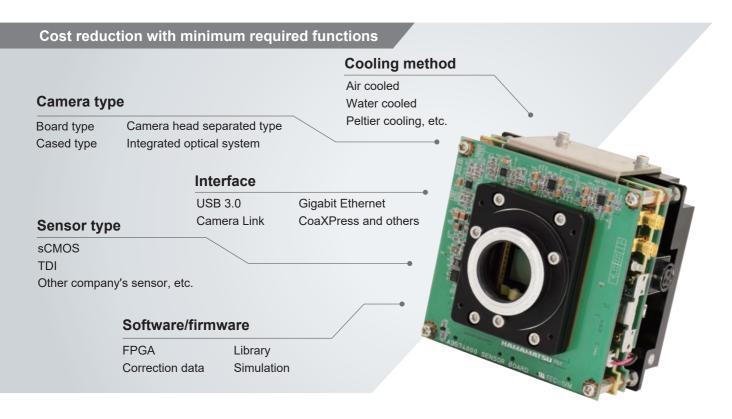
\* Depends on the mode and conditions. For details, refer to each product catalog.

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## **OEM CAMERA**

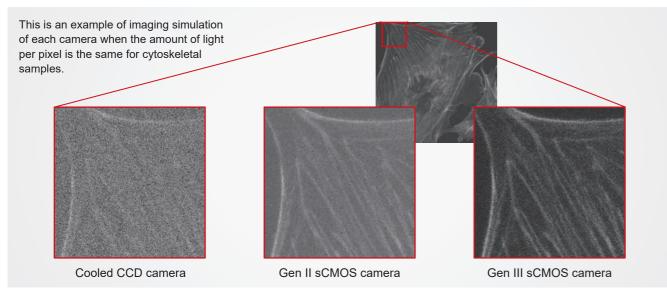
### SOFTWARE

We design and manufacture OEM cameras specific to each customer. We provide various types of cameras with options such as shape, sensor, interface, cooling method, software, etc. to meet customers' requests. The measurement wavelength range covers not only the visible range but spans widely from X-ray to infrared.



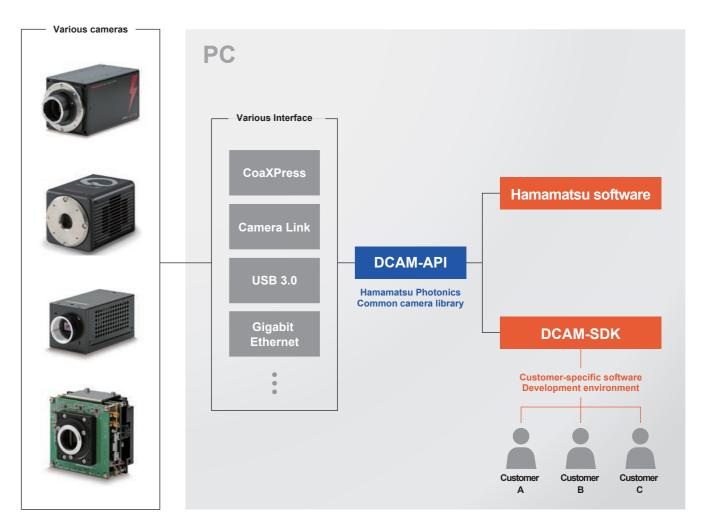
### Simulation technology for prompt realization of OEM

We can perform imaging simulations that match the characteristics (wavelength, sensitivity, speed, etc.) of various cameras. By using this technology, we shorten the process of repeating design and trial production and provide a camera that meets your purpose efficiently and in a short time



According to your request, we can simulate imaging by flexibly changing the acquisition conditions such as exposure time. The results can also be output as a video.

We provide a common camera library "DCAM-API," Hamamatsu Photonics software that can maximize the characteristics of your camera, and a tool "DCAM-SDK," that allows you to build your own control software. Through DCAM-API, even if the camera or interface is changed, the software modification/change can be minimized.



### Compatible software/development environment

The followings are examples of the development environments and software that can be used with our cameras.

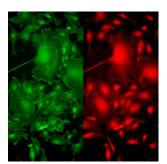
Development environment	Manufacturer	Features				
LabVIEW (Windows)	National Instruments	Simple programming language, easy control of peripheral devices				
MATLAB (Image acquisition toolbox)	The MathWorks	Simple programming language and a rich data analysis library				
Micro-manager®	Open Imaging	A library that enables control of microscopes and peripheral devices of other companies				
Software	Manufacturer	Features				
MetaMorph <sup>®</sup> software suite of products	Molecular Devices	Image processing software for life science field				

\* For details on external software, contact the manufacturer.

# RELATED PRODUCTS

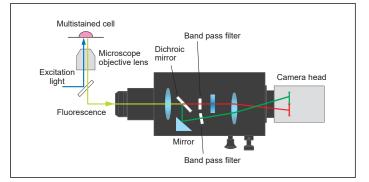
### Image splitting optics W-VIEW GEMINI/W-VIEW GEMINI-2C

W-VIEW GEMINI A12801-01 is an image splitting optical system for a fluorescence microscope that splits incident light into two wavelengths and forms an image on a single camera. You can easily adjust the optical axis and observe images of two wavelengths at the same time. We also have a line-up of W-VIEW GEMINI-2C A12801-10, which forms images on two cameras.





### A two wave lengths image by W-VIEW GEMINI



W-VIEW GEMINI principle diagram

### W-VIEW GEMINI A12801-01

### X-ray line scan camera/X-ray TDI camera

We have a lineup of X-ray non-destructive inspection cameras that can be used in-line. Since it is possible to inspect the inside of substances that cannot be seen with visible light or infrared light, these cameras are suitable for foreign matter inspection of foods and pharmaceuticals, defect inspection of printed circuit board, etc.



### X-ray line scan camera C14300 series

X-ray TDI camera C12300 series

X-ray source Object X-ray line scan Conveyor camera

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